



Material Content Data Sheet



Sales Product Name		BFP 840FESD H6327		Issued		24. January 2018		
MA#		MA001351576						
Package		PG-TSFP-4-1		Weight*		1.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.04		376	
	noble metal	gold	7440-57-5	0.003	0.15		1456	
	inorganic material	silicon	7440-21-3	0.020	1.08	1.27	10792	12624
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79	
	non noble metal	titanium	7440-32-6	0.001	0.04		394	
	non noble metal	chromium	7440-47-3	0.002	0.12		1182	
	non noble metal	copper	7440-50-8	0.734	39.24	39.41	392380	394035
wire	noble metal	gold	7440-57-5	0.008	0.42	0.42	4183	4183
encapsulation	organic material	carbon black	1333-86-4	0.010	0.51		5146	
	plastics	epoxy resin	-	0.207	11.06		110630	
	inorganic material	silicondioxide	60676-86-0	0.746	39.87	51.44	398786	514562
leadfinish	non noble metal	tin	7440-31-5	0.050	2.65	2.65	26484	26484
plating	noble metal	silver	7440-22-4	0.090	4.81	4.81	48112	48112
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com